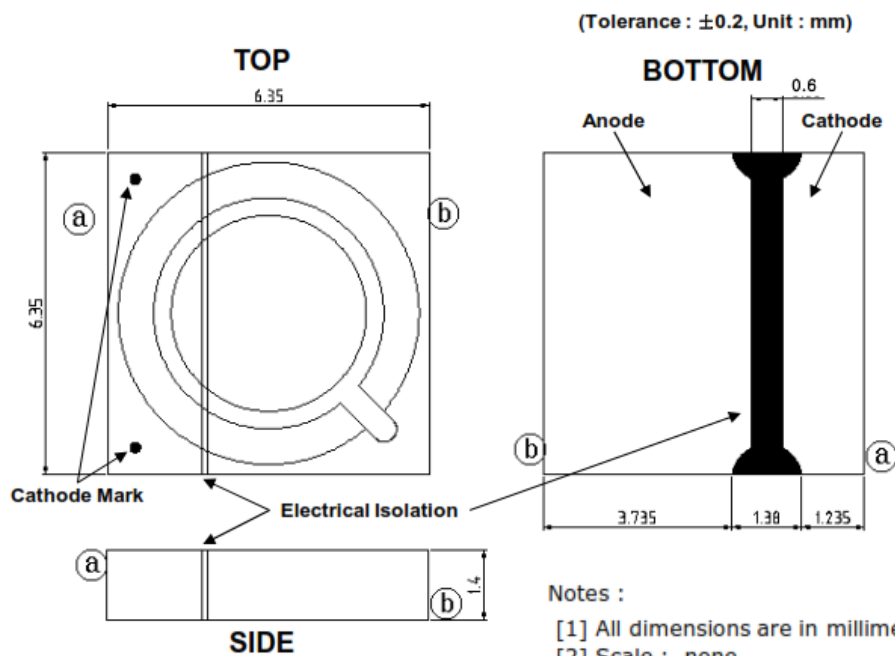
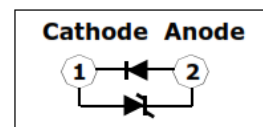


Peak Emission Wavelength: 340nm



< Circuit Diagram >



Material Information	
PKG body	Metal
Lens	Glass

- Notes :
- [1] All dimensions are in millimeters.
 - [2] Scale : none
 - [3] Undefined tolerance is ±0.2mm

Electro-Optical Characteristics (Ta=25°C)



ITEMS	TEST CONDITIONS	SYMBOL	RATINGS	UNIT
Peak Wavelength [1]	500mA	λ_p	340	nm
Radiant Flux [2]	500mA	Φ_e [3]	55	mW
Forward Voltage [4]	500mA	V_f	4.3	V
Spectrum Half Width	500mA	$\Delta \lambda$	11	nm
View Angle	500mA	$2\theta_{1/2}$	110	deg
Thermal Resistance	500mA	$R_{\theta j-b}$ [5]	8.3	°C/W

Notes :

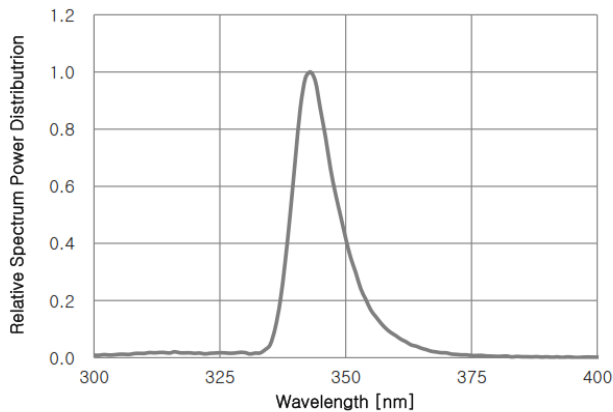
1. Peak Wavelength Measurement tolerance : ±3nm
2. Radiant Flux Measurement tolerance : ± 10%
3. Φ_e is the Total Radiant Flux as measured with an integrated sphere.
4. Forward Voltage Measurement Tolerance: +/-3%.
5. is the thermal resistance between chip junction to PCB board bottom. The PCB is made of aluminum.

Absolute Maximum Ratings

ITEMS	SYMBOL	RATINGS	UNIT
Forward Current	If	500	mA
Junction Temperature	Tj	125	°C
Operating Temperature	Topr	-10 to +85	°C
Storage Temperature	Tstg	-40 to +100	°C

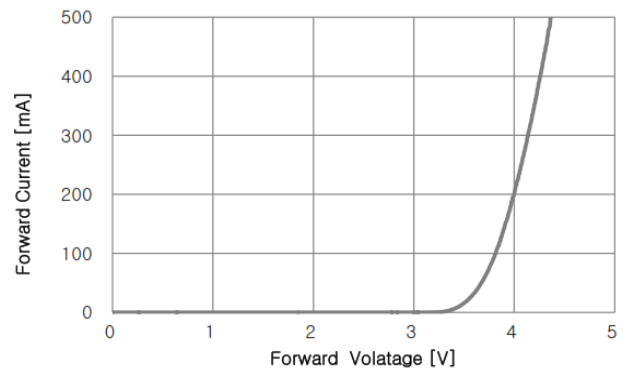
1. Relative Spectral Power Distribution

($I_f=500\text{mA}$, $T_a=25^\circ\text{C}$, $\text{RH}=30\%$)



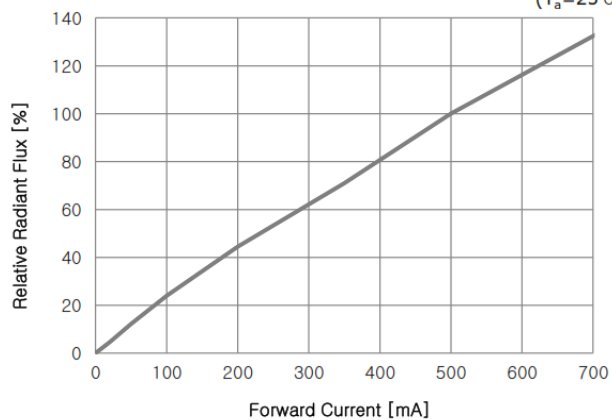
2. Forward Current VS Forward Voltage

($T_a=25^\circ\text{C}$)



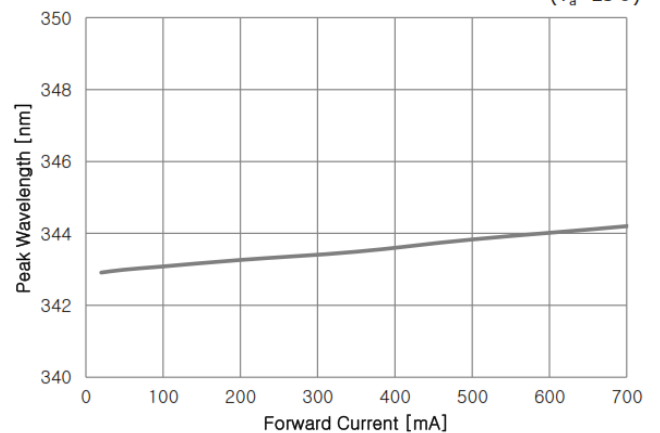
3. Relative Radiant Flux VS Forward Current

($T_a=25^\circ\text{C}$)



4. Peak Wavelength VS Forward Current

($T_a=25^\circ\text{C}$)

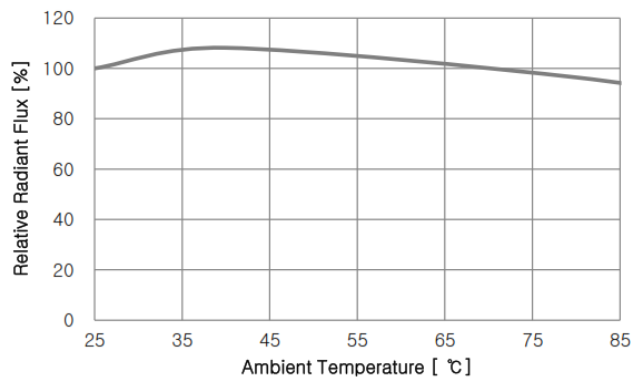


The information contained herein is subject to change without notice.

2017-01-25

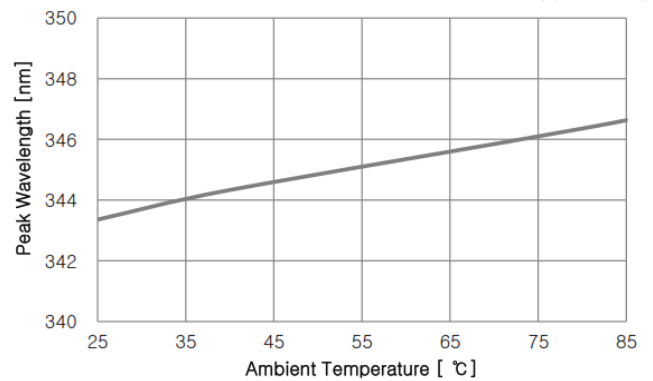
5. Relative Radiant Flux VS Ambient Temperature

($I_F=500\text{mA}$)



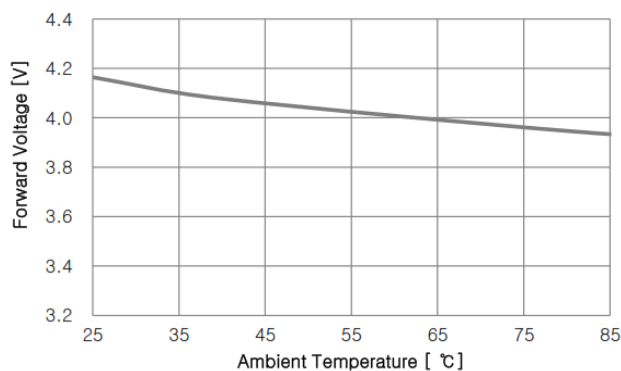
6. Peak Wavelength VS Ambient Temperature

($I_F=500\text{mA}$)



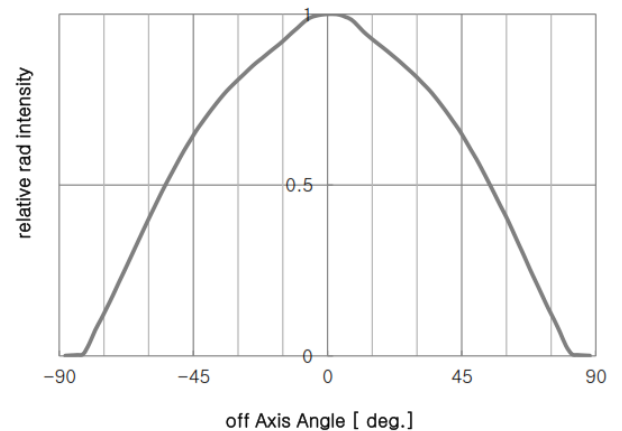
7. Forward Voltage VS Ambient Temperature

($I_F=500\text{mA}$)



8. Radiation pattern

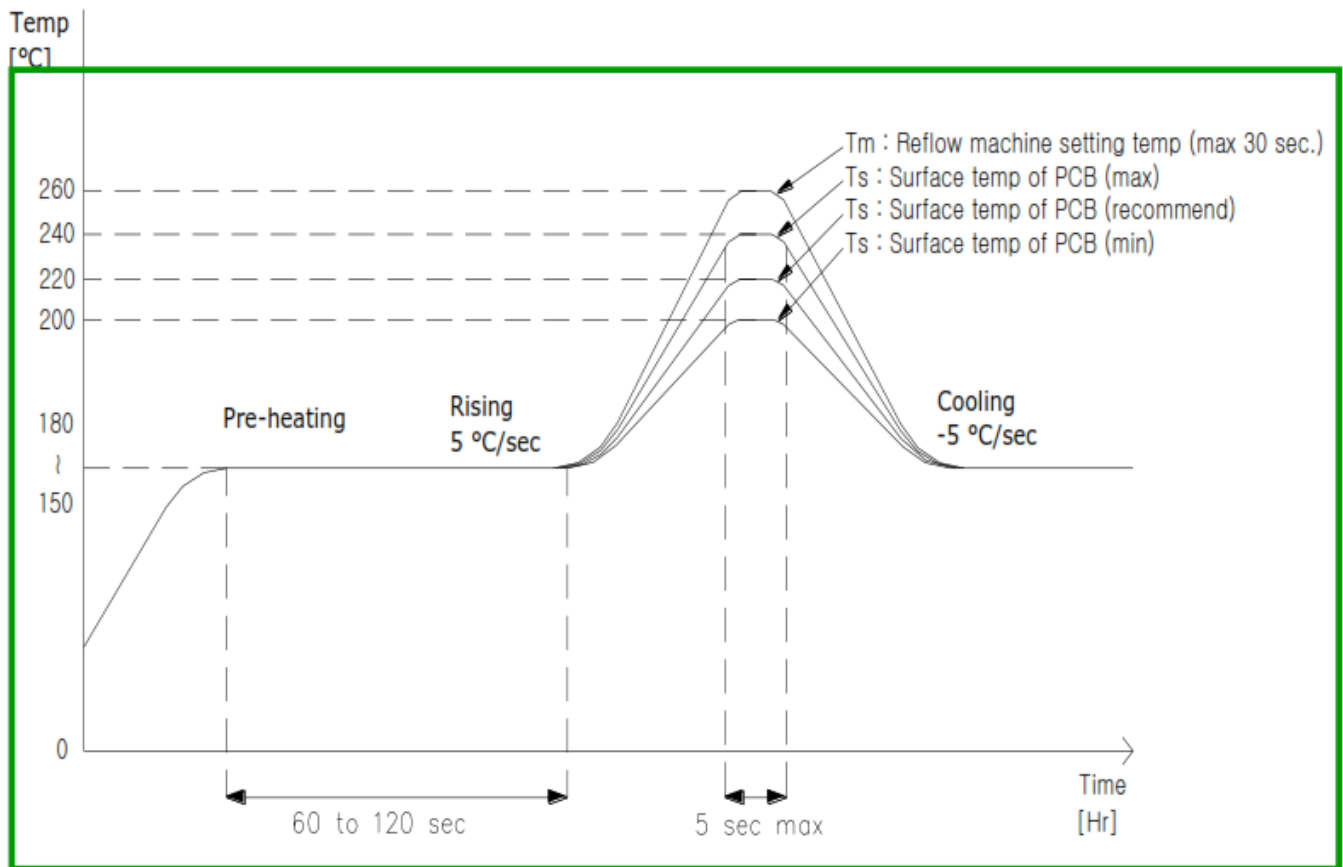
($I_F=500\text{mA}$)



The information contained herein is subject to change without notice.

2017-01-25

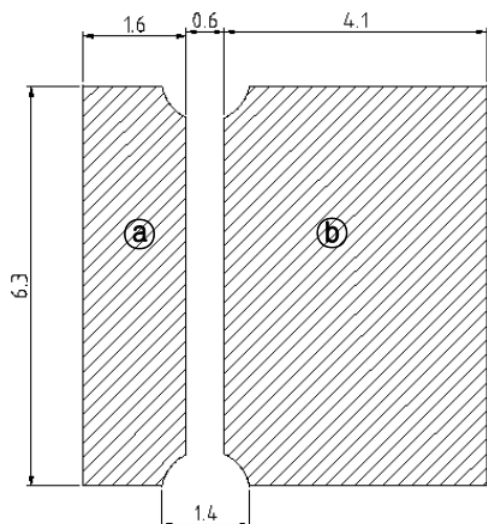
Reflow Soldering Profile



* Caution

1. Reflow soldering should not be done more than one time.
2. Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used.
3. Die slug is to be soldered.
4. When soldering, do not put stress on the LEDs during heating.
5. After soldering, do not warp the circuit board.
6. Recommend to use a convection type reflow machine with 7 ~ 8 zones.

Recommended Solder Pad



Ⓐ : Cathode
Ⓑ : Anode

(Unit :mm)



! CAUTION

1. LEDs emit very strong UV radiation during operation.
2. Don't look directly into the LED light when in operation as UV radiation can harm your eyes.
3. To prevent even inadequate exposure, wear protective eyewear.
4. If LEDs are embedded in devices, please indicate warning labels against the UV LED used.
5. Avoid prolonged exposure to skin or other tissue during operation.
6. Keep out of reach of children.
7. Take appropriate precautions around pets and other living organisms to avoid UV exposure.
8. Specification and dimension are subject to change without notice.